

Display Elektronik GmbH

DATA SHEET

LCD MODULE

**DEM 240320E TMH-PW-N
(A-TOUCH)**

2,4'' TFT with Touch-Panel

Product Specification

Ver.: 1

15.12.2011

Revise Records

Rev.	Date	Contents	Written	Approved
0	10.01.2011	Preliminary Specification	CL	MH
1	15.12.2012	Updated LED current and luminance	MH	MH

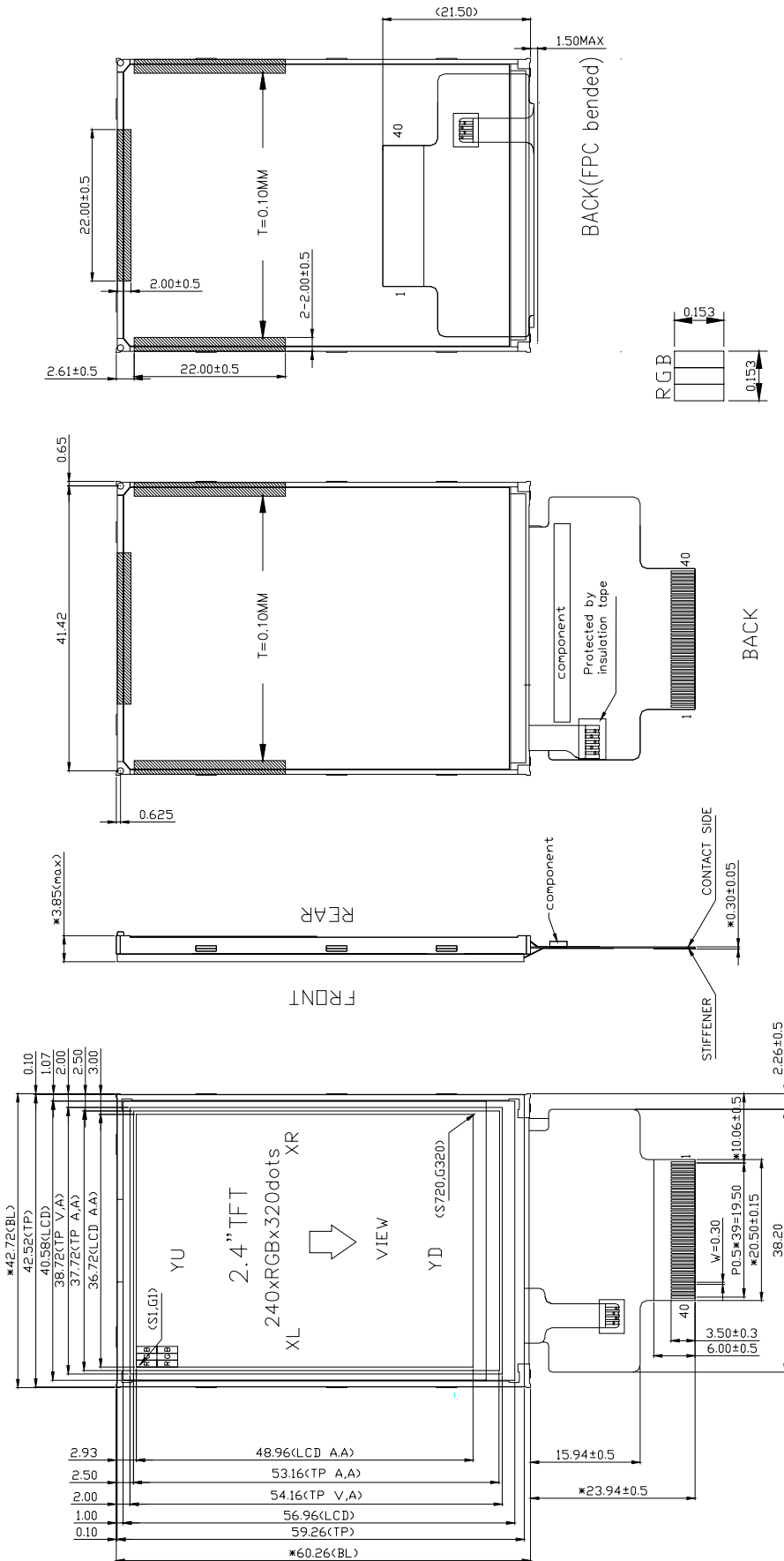
Special Notes

Note1.	
Note2.	
Note3.	
Note4.	
Note5.	

CONTENT

- 1. LCM DRAWING**
- 2. GENERAL DESCRIPTION**
- 3. MECHANICAL SPECIFICATIONS**
- 4. ELECTRO-OPTICAL CHARACTERISTICS**
- 5. BLOCK DIAGRAM**
- 6. ELECTRONIC CHARACTERISTICS**
- 7. PINS DESCRIPTION**
- 8. INSTRUCTION DESCRIPTION**
- 9. BACKLIGHT PARAMETERS**
- 10. PRODUCT QUALITY & RELIABILITY**
- 11. PRECAUTIONS IN USING**
- 12. APPLICATION**

1. LCM DRAWING



2. GENERAL DESCRIPTION

MAIN TECHNICS :	COG
DISPLAY CONTENT :	GRAPHIC
DISPLAY TYPE :	262K COLORS-TFT-NEGATIVE-TRANSMISSIVE
DRIVER METHOD :	1/320 DUTY
VIEWING DIRECTION :	12:00
CONTROLLER:	R61580 (RENESAS)
BACKLIGHT :	LED WHITE
OPEATING TEMPERATURE :	-20°C to +70°C
STORAGE TEMPERATURE :	-30°C to +80°C
INTERFACE:	SPI and 8080 Series MPU(8/16-bit)

3. MECHANICAL SPECIFICATIONS

ITEM	CONTENT	UNIT
PIXEL'S NUMBER	240 x RGB x 320	DOTS
MODULE DIMENSION	42.72 x 60.26 x 4.35	mm
ACTIVE AREA	36.72 x 48.96	mm
PIXEL SIZE	0.153 x 0.153	mm

4. ELECTRO-OPTICAL CHARACTERISTICS

Item	Symbol	Condition	Min.	Typ.	Max.	Unit	Note
Transmittance (without Polarizer)	T(%)	—	—	13.5	—	—	
Contrast Ratio	CR	$\theta=0$	400	500	—	—	(1)(2)
Response time	Rising	T_R	Normal viewing angle	2	4	msec	(1)(3)
	Falling	T_F		6	12		
Color gamut	S(%)			60		%	
Color chromaticity (CIE1931)	White	W_x	TBD	0.308	TBD	(1)(4) CF glass (C-light)	
		W_y	TBD	0.325	TBD		
	Red	R_x	TBD	0.630	TBD		
		R_y	TBD	0.337	TBD		
	Green	G_x	TBD	0.284	TBD		
		G_y	TBD	0.543	TBD		
Blue	B_x	TBD	0.143	TBD			
	B_y	TBD	0.120	TBD			
Viewing angle	Hor.	θ_L	CR>10	TBD	45	—	
		θ_R		TBD	45	—	
	Ver.	θ_U		TBD	45	—	
		θ_D		TBD	20	—	
Optima View Direction	12 O'clock						(5)

*Note (1) Definition of Contrast Ratio (CR):

The contrast ratio can be calculated by the following expression.

$$\text{Contrast Ratio (CR)} = L_{63} / L_0$$

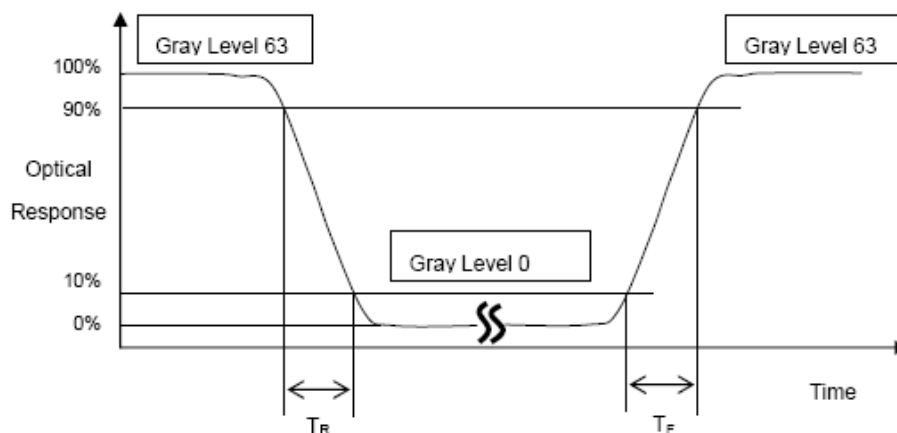
L63: Luminance of gray level 63

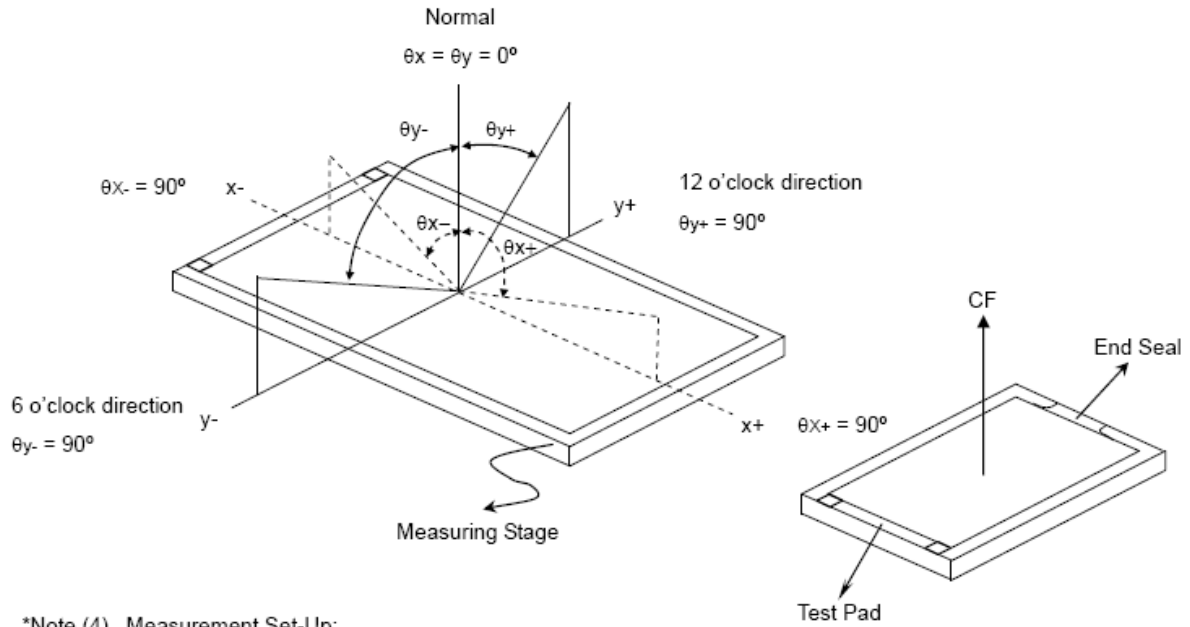
L 0: Luminance of gray level 0

$$CR = CR (5)$$

CR (X) is corresponding to the Contrast Ratio of the point X at Figure in Note (5).

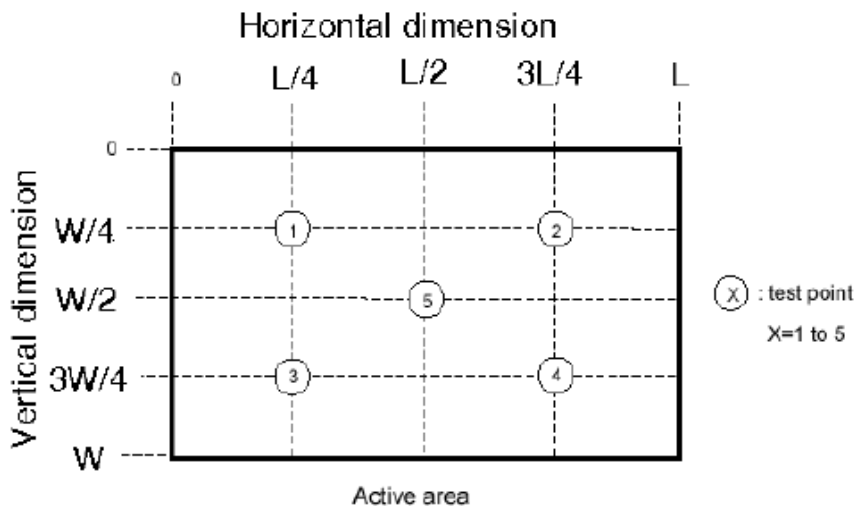
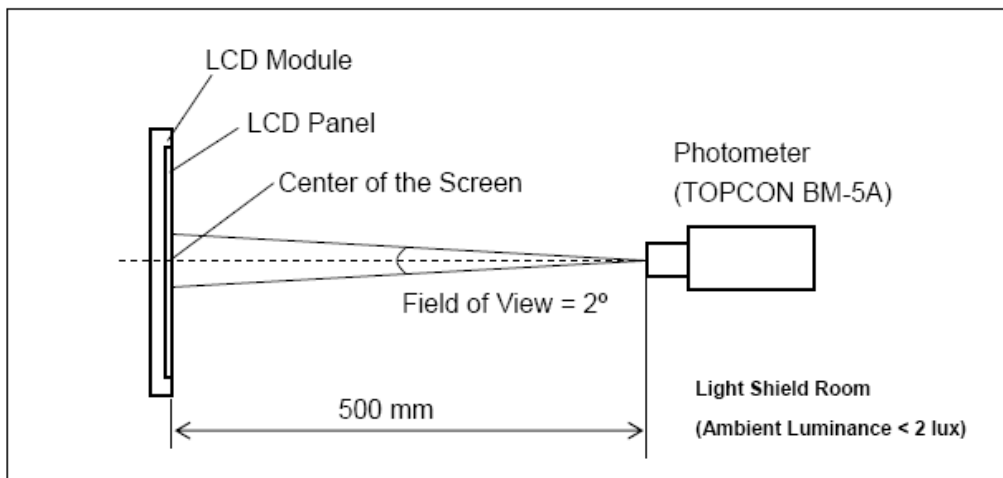
*Note (2) Definition of Response Time (T_R , T_F):



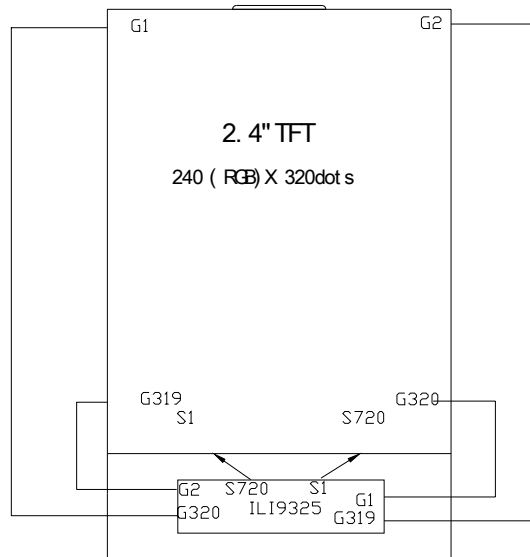


*Note (4) Measurement Set-Up:

The LCD module should be stabilized at a given temperature for 20 minutes to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after lighting Backlight for 20 minutes in a windless room.



5. BLOCK DIAGRAM



6. ELECTRONIC CHARACTERISTICS

6.1 MAXIMUM VALUES

ITEM	SYMBOL	STANDARD VALUE		UNIT
		MIN	MAX	
Logic supply voltage	V _{DD}	-0.3	+4.6	V
Operating Temperature	Top	-20	+70	°C
Storage Temperature	Tst	-30	+80	°C

6.2. DC CHARACTERISTICS

(VCC= 2.50V~3.30V, IOVCC=1.65V~3.30V, Ta=-40C~+85C)

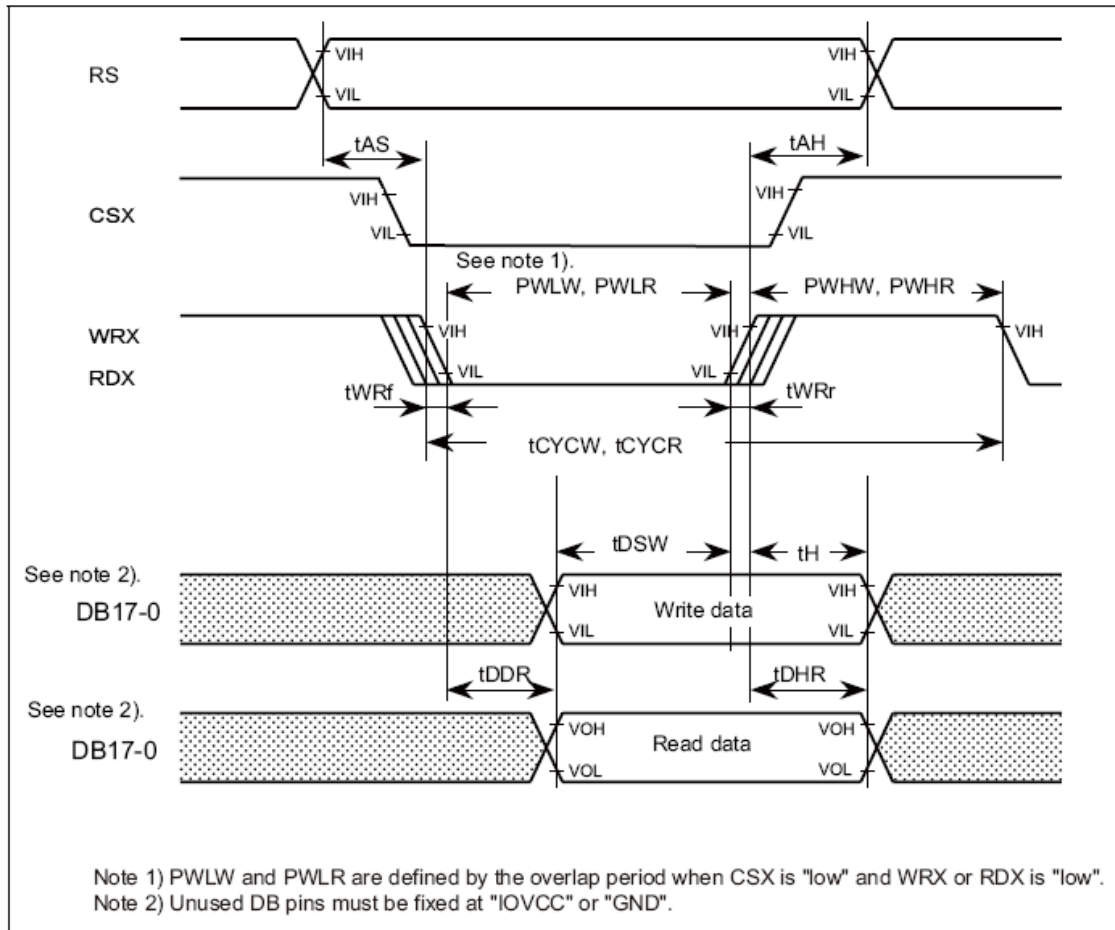
Item	Symbol	Unit	Test Condition	Min.	Typ.	Max.	Note
Input "High" level voltage 1 Except RESETX pin	V _{IH1}	V	IOVCC=1.65V~3.30V	0.80× IOVCC	—	IOVCC	2, 3
Input "Low" level voltage 1 Except RESETX pin	V _{IL1}	V	IOVCC=1.65V~3.30V	-0.3	—	0.20× IOVCC	2, 3
Input "High" level voltage 2 RESETX pin	V _{IH2}	V	IOVCC=1.65V~3.30V	0.90× IOVCC	—	IOVCC	2, 3
Input "Low" level voltage 2 RESETX pin	V _{IL2}	V	IOVCC=1.65V~3.30V	-0.3	—	0.10× IOVCC	2, 3
Output "High" level voltage 1 (DB0-17, FMARK)	V _{OH}	V	IOVCC=1.65V~3.30V, IOH=-0.1mA	0.8× IOVCC	—	—	2
Output "Low" level voltage 1 (DB0-17, FMARK)	V _{OL}	V	IOVCC=1.65V~3.30V, IOL=0.1mA	—	—	0.20× IOVCC	2
Input/Output leakage current	I _{LI}	μA	Vin=0~IOVCC	-1	—	1	4
Current consumption (IOVCC-GND) + (VCC-GND)) Normal operation (260-k color, display operation)	I _{OP1}	mA	fosc=678kHz (320 line drive), IOVCC=VCC=3.00V, fFLM=70Hz, Ta=25°C, Frame memory data: 18'h000000, BLCON=0, See below for other information	—	0.6	TBD	5
Current consumption (IOVCC-GND) + (VCC-GND)) Normal operation (260-k color, display operation), BLC ON	I _{OP1}	mA	fosc=678kHz (320 line drive), IOVCC=VCC=3.00V, fFLM=70Hz, Ta=25°C, Frame memory data: 18'h000000, BLCON=1, See below for other information	—	0.8	TBD	5
Current consumption (IOVCC-GND) + (VCC-GND)) 8-color mode (64 line partial display operation)	I _{OP2}	μA	fosc=678kHz (64 line partial display operation), IOVCC=VCC=3.00V, fFLM=40Hz, Ta=25°C, Frame memory data: 18'h000000, BLCON=0, See below for other information	—	140	—	5
Current consumption (IOVCC-GND) + (VCC-GND)) Deep standby mode	I _{DST}	μA	IOVCC=VCC=3.00V, Ta=25°C	—	0.1	TBD	5

Item	Symbol	Unit	Test Condition	Min.	Typ.	Max.	Note
Current consumption ($(I_{OVCC-GND}) + (VCC-GND)$) Frame memory access mode	I_{RAM1}	mA	IOVCC=2.40V, VCC=3.00V, tCYCW=125ns, Ta=25°C, 180-8bit-I/F, TRIREG=1'h1, Consecutive frame memory access during display operation	—	2.6	—	5
LCD power supply current (VCI-GND) 260-k color display operation	Ici1	mA	IOVCC=1.8V, VCC=VCI=2.8V, 320 line drive, fFLM=60Hz, Ta=25°C, Frame memory data: 18'h00000, REV=0, BC0=0, FP0=8, BP0=8, VC=3'h1, BT=3'h4, VRH=5'h18, VCM=7'h7F, VDV=5'h11, AP0=2'h3, DC00=3'h4, DC10=3'h4 PR*P00=PR*N00=5'h00, PR*P01=PR*N01=5'h02, PR*P02=PR*N02=5'h04, PR*P03=PR*N03=4'h8, PR*P04=PR*N04=4'hF, PR*P05=PR*N05=4'h8, PR*P06=PR*N06=5'h04, PR*P07=PR*N07=5'h02, PR*P08=PR*N08=5'h04, PIR*P0= PIR*P1= PIR*P2= PIR*P3=2'h0 PIR*N0= PIR*N1= PIR*N2= PIR*N3=2'h0 (*: 0, 1, 2), No load on the panel	—	3.2	TBD	5
LCD power supply current (VCI-GND) 8-color display operation (64 line partial display)	Ici2	mA	IOVCC=1.8V, VCC=VCI=2.8V, 64 line partial display, fFLM=40Hz, Ta=25°C, Frame memory data: 18'h00000, REV=0, BC2=0, FP2=5, BP2=8, VC=3'h1, BT=3'h4, VRH=5'h18, VCM=7'h7F, VDV=5'h11, AP2=2'h3, DC02=3'h4, DC12=3'h2, PR*P00=PR*N00=5'h00, PR*P01=PR*N01=5'h02, PR*P02=PR*N02=5'h04, PR*P03=PR*N03=4'h8, PR*P04=PR*N04=4'hF, PR*P05=PR*N05=4'h8, PR*P06=PR*N06=5'h04, PR*P07=PR*N07=5'h02, PR*P08=PR*N08=5'h04, PIR*P0= PIR*P1= PIR*P2= PIR*P3=2'h0 PIR*N0= PIR*N1= PIR*N2= PIR*N3=2'h0 (*: 0, 1, 2), No load on the panel, COL=0	—	0.8	—	5
Output voltage dispersion	ΔVO	mV	—	—	5	—	6
Average output variance	$\Delta V\Delta$	mV	—	-35	—	35	7

Item	Unit	Test condition	Min.	Typ.	Max.	Note	
Step-up output voltage	DDVDH	V	IOVCC=VCC=2.8V, VCI =2.8V, Ta=25°C, VC=3'h1, BT=3'h4, AP=2'h3, DC0=3'h3, DC1=3'h2, C11=C12=C13=C21=C22=1[uF]/B characteristics, DDVDH=VGH=VGL=VCL=1[uF]/B characteristics, No load on the panel, Iload1=-3 [mA]	4.8	5.1	-	
	VGH	V	IOVCC=VCC=2.8V, VCI =2.8V, Ta=25°C, VC=3'h1, BT=3'h4, AP=2'h3, DC0=3'h3, DC1=3'h2, C11=C12=C13=C21=C22=1[uF]/B characteristics, DDVDH=VGH=VGL=VCL=1[uF]/B characteristics, Iload2=-100[uA], No load on the panel	14.4	15.1	-	
	VGL	V	IOVCC=VCC=2.8V, VCI =2.8V, Ta=25°C, VC=3'h1, BT=3'h4, AP=2'h3, DC0=3'h3, DC1=3'h2, C11=C12=C13=C21=C22=1[uF]/B characteristics, DDVDH=VGH=VGL=VCL=1[uF]/B characteristics, Iload3=+100[uA], No load on the panel	-	-10.0	-9.6	
	VCL	V	IOVCC=VCC=2.8V, VCI =2.8V, Ta=25°C, VC=3'h1, BT=3'h4, AP=2'h3, DC0=3'h3, DC1=3'h2, C11=C12=C13=C21=C22=1[uF]/B characteristics, DDVDH=VGH=VGL=VCL=1[uF]/B characteristics, Iload4=+200[uA], No load on the panel	-	-2.55	-2.4	

6.3 . TIMING CHARACTERISTICS

80-System Bus Interface



80-System Bus Interface Timing Characteristics (18-/16-bit Interface)

Table 103 (IOVCC=1.65V ~ 3.30V) (T.B.D.)

Item		Symbol	Unit	Timing Diagram	Min.	Typ.	Max.
Bus cycle time	Write	tcycw	ns	Figure A	75	-	-
	Read	tcycr	ns	Figure A	450	-	-
Write low-level pulse width		PWLW	ns	Figure A	40	-	-
Read low-level pulse width		PWLR	ns	Figure A	170	-	-
Write high-level pulse width		PWHW	ns	Figure A	25	-	-
Read high-level pulse width		PWHR	ns	Figure A	250	-	-
Write / Read rise/ fall time		t _{WRr} , t _{WRf}	ns	Figure A	-	-	25
Setup time	Write (RS to CSX, WRX)	t _{AS}	ns	Figure A	0	-	-
	Read (RS to CSX, RDX)		ns	Figure A	10	-	-
Address hold time		t _{AH}	ns	Figure A	2	-	-
Write data setup time		t _{DSW}	ns	Figure A	25	-	-
Write data hold time		t _H	ns	Figure A	10	-	-
Read data delay time		t _{DDR}	ns	Figure A	-	-	150
Read data hold time		t _{DHR}	ns	Figure A	5	-	-

Note: The above values are target values. They are subject to change.

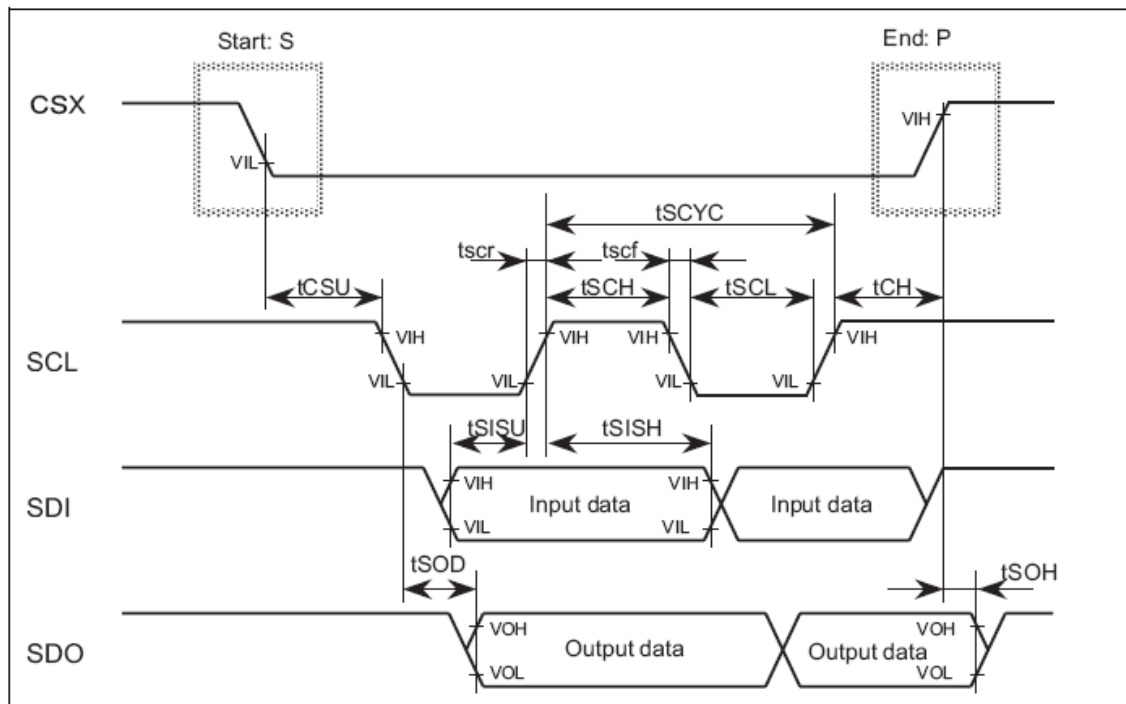
80-System Bus Interface Timing Characteristics (9-/8-bit Interface)

Table 104 (IOVCC=1.65V ~ 3.30V) (T.B.D.)

Item		Symbol	Unit	Timing Diagram	Min.	Typ.	Max.
Bus cycle time	Write	tcycw	ns	Figure A	70	—	—
	Read	tcycr	ns	Figure A	450	—	—
Write low-level pulse width		PWLW	ns	Figure A	30	—	—
Read low-level pulse width		PWLR	ns	Figure A	170	—	—
Write high-level pulse width		PWHW	ns	Figure A	25	—	—
Read high-level pulse width		PWHR	ns	Figure A	250	—	—
Write / Read rise/ fall time		t _{WRr} , t _{WRf}	ns	Figure A	—	—	25
Setup time	Write (RS to CSX, WRX)	t _{AS}	ns	Figure A	0	—	—
	Read (RS to CSX, RDX)		ns	Figure A	10	—	—
Address hold time		t _{AH}	ns	Figure A	2	—	—
Write data setup time		t _{DSW}	ns	Figure A	25	—	—
Write data hold time		t _H	ns	Figure A	10	—	—
Read data delay time		t _{DDR}	ns	Figure A	—	—	150
Read data hold time		t _{DHR}	ns	Figure A	5	—	—

Note: The above values are target values. They are subject to change.

Clock Synchronous Serial Interface



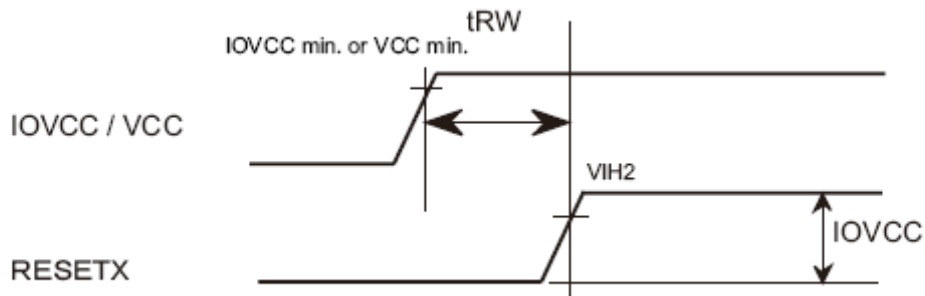
Clock Synchronous Serial Interface Timing Characteristics

Table 105 (IOVCC=1.65V ~ 3.30V) (T.B.D.)

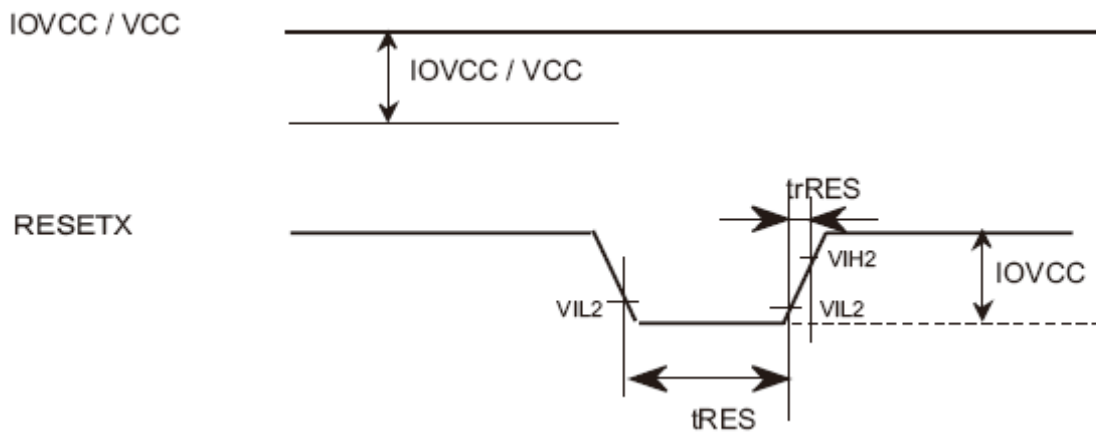
Item		Symbol	Unit	Timing Diagram	Min.	Typ.	Max.
Serial clock cycle time	Write (receive)	tscyc	ns	Figure B	100	—	20,000
	Read (transmit)	tscyc	ns	Figure B	350	—	20,000
Serial clock high-level width	Write (receive)	tsch	ns	Figure B	40	—	—
	Read (transmit)	tsch	ns	Figure B	150	—	—
Serial clock low-level width	Write (receive)	tscl	ns	Figure B	40	—	—
	Read (transmit)	tscl	ns	Figure B	150	—	—
Serial clock rise/fall time		tscr, tscf	ns	Figure B	—	—	20
Chip select setup time		tcsu	ns	Figure B	20	—	—
Chip select hold time		tch	ns	Figure B	60	—	—
Serial input data setup time		tsisu	ns	Figure B	30	—	—
Serial input data hold time		tsish	ns	Figure B	30	—	—
Serial output data delay time		tsod	ns	Figure B	—	—	130
Serial output data hold time		tsoh	ns	Figure B	5	—	—

Note: The above values are target values. They are subject to change.

Reset timing when power supply is input



Reset timing during normal operation



Reset Timing Characteristics

Table 106 (IOVCC = 1.65V ~ 3.30V) (T.B.D.)

Item	Symbol	Unit	Timing Diagram	Min.	Typ.	Max.
Reset wait time	tRW	ms	Figure C-1	1	—	—
Reset low-level width	tRES	ms	Figure C-2	1	—	—
Reset rise time	trRES	μs	Figure C-2	—	—	10

Note: The above values are target values. They are subject to change.

7. PINS DESCRIPTION

Pin No.	Symbol	Description																
1	NC	NC																
2	LEDA4	Backlight LED anode (A4)																
3	LEDA3	Backlight LED anode (A3)																
4	LEDA2	Backlight LED anode (A2)																
5	LEDA1	Backlight LED anode (A1)																
6	LEDK	Backlight LED cathode																
7	IM0	Select the MPU system interface mode <table border="1"> <thead> <tr> <th></th> <th>8bit DB[17:10]</th> <th>16bit DB[17:10], DB[8:1]</th> <th>SPI</th> </tr> </thead> <tbody> <tr> <td>IM0</td> <td>1</td> <td>0</td> <td>0</td> </tr> <tr> <td>IM1</td> <td>1</td> <td>1</td> <td>0</td> </tr> <tr> <td>IM2</td> <td>0</td> <td>0</td> <td>1</td> </tr> </tbody> </table>		8bit DB[17:10]	16bit DB[17:10], DB[8:1]	SPI	IM0	1	0	0	IM1	1	1	0	IM2	0	0	1
	8bit DB[17:10]		16bit DB[17:10], DB[8:1]	SPI														
IM0	1		0	0														
IM1	1		1	0														
IM2	0	0	1															
8	IM1																	
9	IM2																	
10	/RESET	L: initialization is executed																
11-18	DB[17:10]	Data bus																
19-26	DB[8:1]	Data bus																
27	SDO	SPI interface output pin																
28	SDI	SPI interface input pin																
29	/RD	I80 system:Serves as a read signal and reads data at the low level																
30	/WR/SCL	I80 system:Serves as a write signal and writes data at the rising edge SPI Mode:Synchronizing clock signal in SPI mode																
31	RS	L:Command;H:display data																
32	/CS	L:Chip Selected H:Chip Unselected																
33	VCC	I/O interface supply voltage 3.3V																
34	GND	Ground																
35	VCI	Analog power supply voltage 3.3V																
36	XR	touch panel output pin. (Touch screen X coordinate right XR)																
37	YD	touch panel output pin. (Touch screen Y coordinate down YD)																
38	XL	touch panel output pin. (Touch screen X coordinate left XL)																
39	YU	touch panel output pin. (Touch screen Y coordinate up YU)																
40	NC	NC																

8. INSTRUCTION DESCRIPTION

Major category	Minor category	Index	Upper Code										Lower Code										Note											
	Command		IB15	IB14	IB13	IB12	IB11	IB10	IB9	IB8	IB7	IB6	IB5	IB4	IB3	IB2	IB1	IB0	IB15	IB14	IB13	IB12	IB11	IB10	IB9	IB8	IB7	IB6	IB5	IB4	IB3	IB2	IB1	IB0
0*	Display Control	00h	ALM0[7]	ALM0[6]	ALM0[5]	ALM0[4]	ALM0[3]	ALM0[2]	ALM0[1]	ALM0[0]	ALM03[7]	ALM03[6]	ALM03[5]	ALM03[4]	ALM03[3]	ALM03[2]	ALM03[1]	ALM03[0]																
		01h									SS																							
	Display Control	02h								ECO																								
		03h	THREG	DFM	0	BGR	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0		
	Display Control	07h								BASE																								
		08h	FRQ7	FRQ6	FRQ5	FRQ4	FRQ3	FRQ2	FRQ1	FRQ0	FRQ7	FRQ6	FRQ5	FRQ4	FRQ3	FRQ2	FRQ1	FRQ0																
	Display Control	09h								PTIS0																								
		0Ah								PTIS1																								
	Display Control	0Ch								EMG0																								
		0Dh								EMG1																								
	Display Control	0Eh								EMR0																								
		0Fh								EMR1																								
Power Control	10h								VDV0																									
	11h								VDV1																									
Power Control	12h								VDV2																									
	13h								VDV3																									
Frame Memory Access Control	20h								AD7																									
	21h								AD8																									
NVW Write Control	22h								AD9																									
	28h								AD10																									
Gamma Control	29h								AD11																									
	2Ah								AD12																									
Gamma Control	30h								AD13																									
	31h								AD14																									
Gamma Control	32h								AD15																									
	33h								AD16																									
Gamma Control	34h								AD17																									
	35h								AD18																									
Gamma Control	36h								AD19																									
	37h								AD20																									
Gamma Control	38h								AD21																									
	39h								AD22																									

Frame memory write data WD[17:0] are transferred via different data bus in different interface operations.

9. BACKLIGHT PARAMETERS**9.1 ABSOLUTE MAXIMUM RATINGS**

(Unless specified, The Ambient temperature Ta=25°C)

Item	Symbol	Condition	Rating	Unit
Operating temperature range	Topr		-20~+70	°C
Storage temperature range	Tst		-30~+80	°C

9.2 ELECTRICAL/OPTICAL CHARACTERISTICS

(Unless specified, The Ambient temperature Ta=25°C)

Item	Symbol	min	typ	max	Unit	Condition
Forward Voltage	Vf	2.9	3.2	3.5	V	If=60mA
Luminance	Lv	3500			cd/m ²	If=60mA
color coordinate	X	0.26		0.30		If=60mA
	Y	0.26		0.30		

10. Product Quality & Reliability

10.1 Standard for Quality Test

10.1.1 Inspection :

Before delivering, the supplier should take the following tests, and affirm the quality of product.

10.1.2 Electro-Optical Characteristics:

According to the individual specification to test the product.

10.1.3 Test of Appearance Characteristics:

According to the individual specification to test the product.

10.1.4 Test of Reliability Characteristics:

According to the definition of reliability on the specification for testing products.

10.1.5 Delivery Test:

Before delivering, the supplier should take the delivery test.

A. Test method: According to GB/2828, General Inspection Level take a single time.

B. The defects classify of AQL as following:

Major defect: AQL=0.25

Minor defect: AQL=1.0

Total defects: AQL=1.0

10.2 Standard for inspection

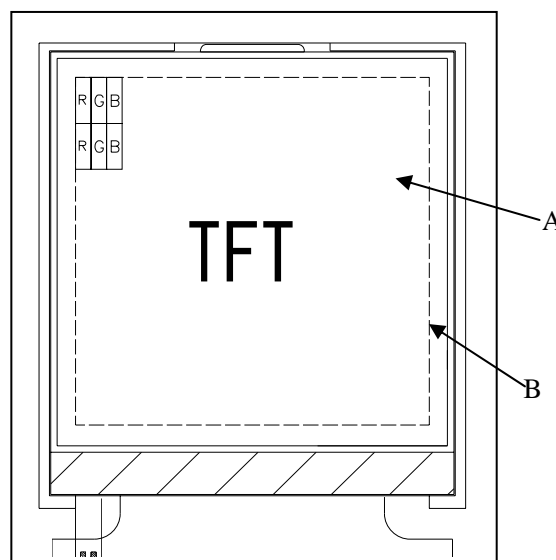
10.2.1 Manner of appearance test:

- The test must be under a 40W fluorescent light, and the distance of view must be at 30~35 cm.
- When test the model of transmissive product must add the reflective plate.
- The test direction is base on about around 45° of vertical line.

10.2.2 Definition of area: A B

A Area : Viewing area.

B Area : Out of viewing area.(Outside viewing area)



10.2.3 Basic principle:

- In principle the defect out of Area A should be acceptable if the defect does not

affect assemblage and the quality of productions.

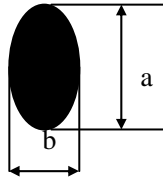
B. If defects that can not describe clearly, acceptable samples will be the standard.

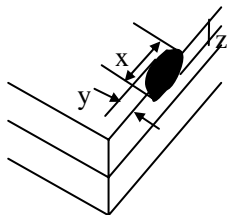
C. The sample of the lowest acceptable quality level must be discussed by both supplier and customer when any dispute happened.

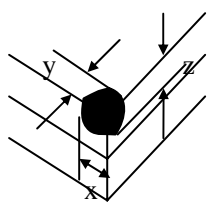
D. Must add new item on time when it is necessary.

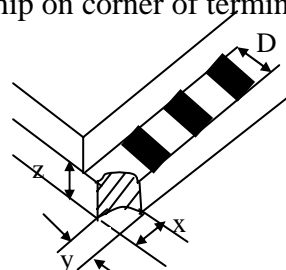
10.2.4 Standard of inspection

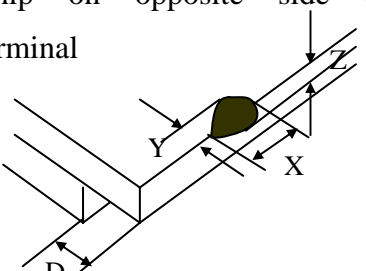
Defect	Inspect item	Criteria
1 Minor	Scratch and fold on polarizer. Scratch on glass. Glass fiber etc. (by bare eyes , defect outside A area is acceptable)	1) width ≤ 0.02 mm length ignore acceptable 2) 0.02 mm < width ≤ 0.05 mm length ≤ 3 mm two are acceptable 3) width > 0.05 mm reject

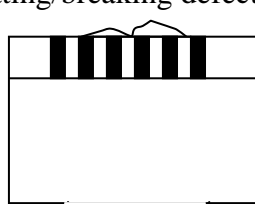
Defect	Inspect item	Criteria
2 Minor	Chip on glass(round type) Chip on polarizer(round type) Air bubble between polarizer and glass  $\Phi = (a + b) / 2$	$\Phi \leq 0.1\text{mm}$ acceptable $0.1 < \Phi \leq 0.2\text{mm}$ two are acceptable 1.The distance between any two dots should be more than 5mm. 2.Defect outside A area is acceptable. 3.If the air bubble is black, it can be judged as black spot.

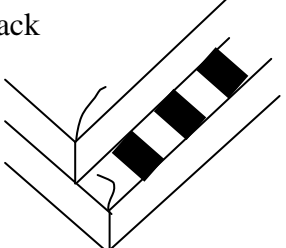
Defect	Inspect item	Criteria
3 Minor	Chip out  x: length y: width z: thickness	$x \leq 3\text{ mm}$ $z \leq t$ $y \leq 1/3 s$ reject t: glass thickness. S: distance between glass edge and inside of edge sealing

Defect	Inspect item	Criteria
4 Minor	<p>Chip on corner of neat edge</p>  <p>X: length Y: width S: width of edge sealing</p>	<p>$x \leq 3 \text{ mm}$ $y \leq 3 \text{ mm}$ $z \leq t$</p> <p>acceptable</p> <p>any chip exposes the silver dot reject</p>

Defect	Inspect item	Criteria
5 Minor	<p>Chip on corner of terminal edge</p>  <p>D: terminal length</p>	<p>$x < 0.3 \text{ mm}$ or $y < 0.3 \text{ mm}$ ignore</p> <p>$x \leq 3 \text{ mm}$ $y < D$ two are acceptable</p>

Defect	Inspect item	Criteria
6 Minor	<p>Chip on opposite side of terminal</p> 	<p>$a \geq 80 \text{ mm}$, $x \geq 7 \text{ mm}$ reject</p> <p>$a < 80 \text{ mm}$, $x > 5 \text{ mm}$ reject</p> <p>$y > 1/2 D$ reject</p> <p>$z > 1/2 t$, $y > 1/4 D$ reject</p> <p>D: terminal length</p>

Defect	Inspect item	Criteria
7 Minor	<p>Cutting/breaking defect (flare)</p> 	<p>According to the dimension of drawing</p>

Defect	Inspect item	Criteria
8 Minor	Crack 	Any crack trend to extend reject

Defect	Inspect item	Criteria
9 Major	Liquid leakage, open sealant	reject

Defect	Inspect item	Criteria
10 Minor	Rainbow	According to samples

Defect	Inspect item	Criteria
11 Major	FPC, TCP, FLEX are broken or not connected firmly	reject

Defect	Inspect item	Criteria
12 Minor	The component on PCB or FPC is missing ,soldered unfirmly or bridged	reject

Defect	Inspect item	Criteria
13 Minor	The soldering tin is not enough	The height that soldering tin covers the bump of component is 1/2 less than the height of bump reject

Defect	Inspect item	Criteria
14 Minor	The soldering tin overflows	The soldering tin covers whole bump reject

Defect	Inspect item	Criteria
15 Minor	The component is broken	reject

Defect	Inspect item	Criteria
16 Minor	The shape of pinouts is not the same as that in the criterion	It makes the LCM work badly reject

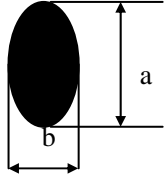
Defect	Inspect item	Criteria
17 Minor	The pinout is broken	reject

Defect	Inspect item	Criteria
18 Minor	The frame is scratched visibly	Length ignore Width >0.5mm reject

Defect	Inspect item	Criteria
19 Minor	The frame is rusted (accumulation)	When the shape is as dot,reference to defect 23 When the shape is as line,reference to defect 24

Defect	Inspect item	Criteria
20 Minor	Scratch and fold on touchpanel. (by bare eyes ,defect outside A area is acceptable)	1) width≤0.02 mm acceptable 2) 0.02 mm<width≤0.05 mm length≤5 mm two are acceptable 3) width>0.05 mm reject

Defect	Inspect item	Criteria
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<p>21 Minor</p>	<p>Black & white dots on touchpanel (round type) Air bubble on touchpanel</p>  <p>$\Phi=(a + b)/2$</p>	<p>1) $\Phi \leq 0.1$ mm acceptable 2) $0.1 < \Phi \leq 0.3$ mm three are acceptable 3) $\Phi > 0.3$ mm reject</p> <p>1.The distance between any two dots should be more than 5mm. 2.Defect outside A area is acceptable. 3.If the air bubble is black, it can be judged as black spot.</p>
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Defect	Inspect item	Criteria
<p>22 Minor</p>	<p>Touchpanel warps</p>	<p>According to the dimension of drawing.</p>

Defect	Inspect item	Criteria
<p>23 Minor</p>	<p>Dirty on rear of touchpanel</p>	<p>It's visible at condition of 30 ± 5 cm, 45°</p>

Defect	Inspect item	Criteria
<p>24 Minor</p>	<p>Dirty on rear of touchpanel</p>	<p>It's visible at condition of 30 ± 5 cm, 45°</p>

10.3 RELIABILITY

Item	Condition	Criterion
High temperature operation	70°C , 96 hrs	-Cosmetic defects are not allowed after the test(Polarizer change is exceptional) -Contrast ratio change over 50% of initial value should not be happened -The current consumption should be below double of initial value -Brightness decrease should be lower than 50% of initial value
Low temperature operation	-20°C , 96 hrs	
Moisture storage	60°C , 90%RH, 96 hrs	
High temperature storage	80°C , 96 hrs	
Low temperature storage	-30°C , 96 hrs	
Thermal shock	-30°C (30 minute) 25°C (5 minute) 80°C (30 minute) CYCLES: 10	
LIFE TIME	50,000 hours, 25±10°C, 45±20% RH	

11. PRECAUTIONS IN USING

11.1 Liquid crystal display (LCD)

The LCD panel is made up of glass, organic fluid and polarizer. When handling, please pay attention to the following items:

- 1) Keep the operation and storage temperature of the LCD within the range specified in the LCD specification. Otherwise, excessive temperature and humidity would cause polarization degradation, bubble generation or polarizer peel-off.
- 2) Prevent it from mechanical shock by dropping it from a high place, etc.
- 3) Don't contact, push or rub the exposed polarizers with anything harder than HB pencil lead.
- 4) Avoid using chemicals such as acetone, toluene, ethanol and isoropylalcohol to clean the front/rear polarizers and reflectors, which will cause damage to them.
- 5) Wipe off saliva or water drops immediately. Contact with water over a long period of time may cause deformation or color fading. The LCM is assembled and adjusted with a high degree of precision.
- 6) Do not put or attach anything on the display area. Avoid touching the display area with bare hand.

11.2 Precaution for handling LCD modules

The LCM is assembled and adjusted with a high degree of precision, do not applying excessive shocks to it or making any alterations or modifications to it, the following precautions should be taken when handing.

- 1) Do not drop, bend or twist the module.
- 2) Do not alter or making any modification on the shape of the metal frame.
- 3) Do not change the shape, the pattern wiring or add any extra hole on the PCB.
- 4) Do not modify or touch the zebra rubber strip(conductive rubber) with another object.
- 5) Do not change the positions of components on the PCB.

11.3 Electro-static discharge control

Careful attention should be paid to control the electrostatic discharge of the modules, since the modules contain no. of CMOS LSI.

- 1) Make sure you are grounded properly when remove the module from its antistatic bag. Be sure that the module and have the same electric potential.
- 2) Only properly grounded soldering iron should be used.
- 3) Modules should be stored in antistatic bag or other containers resistant to static after remove from its original package.
- 4) When using the electric screw-driver is used, make sure the screw driver had been ground potentiality to minimize the transmission of EM wave produced by commutator sparks.
- 5) In order to reduce the generation of static electricity, a relative humidity of 50-60% is recommended.

11.4 Precaution for soldering

- 1) Soldering should apply to I/O terminals only.
- 2) Soldering temperature is $280^{\circ}\text{C}+(-)10^{\circ}\text{C}$.
- 3) Soldering time 3-4 seconds.
- 4) Eutectic solder (rosin flux filled) should be used.
- 5) If soldering flux is used, be sure to remove any remaining flux after finishing the soldering operation and LCD surface should be covered during soldering to prevent any damage to flux spatters.
- 6) When remove the lead wires from the I/O terminals, use proper de-soldering methods, e.g. suction type de-soldering irons. Do not repeat wiring by soldering more than three times at the pads and plated though holes may be damaged.

11.5 Precaution for operation

- 1) Adjust liquid crystal driving voltage (V_o) to varies viewing angle and obtain the contrast.
- 2) V_o should be kept in proper range stated in the specification. Excess voltage will shorten the LCD life.
- 3) Response time is greatly delayed at low temperature. It will recover when go back to normal temperature.
- 4) Condensation on terminals can cause an electrochemical reaction disrupting the terminal circuit. Therefore it should be used under the relative condition of 50% RH.

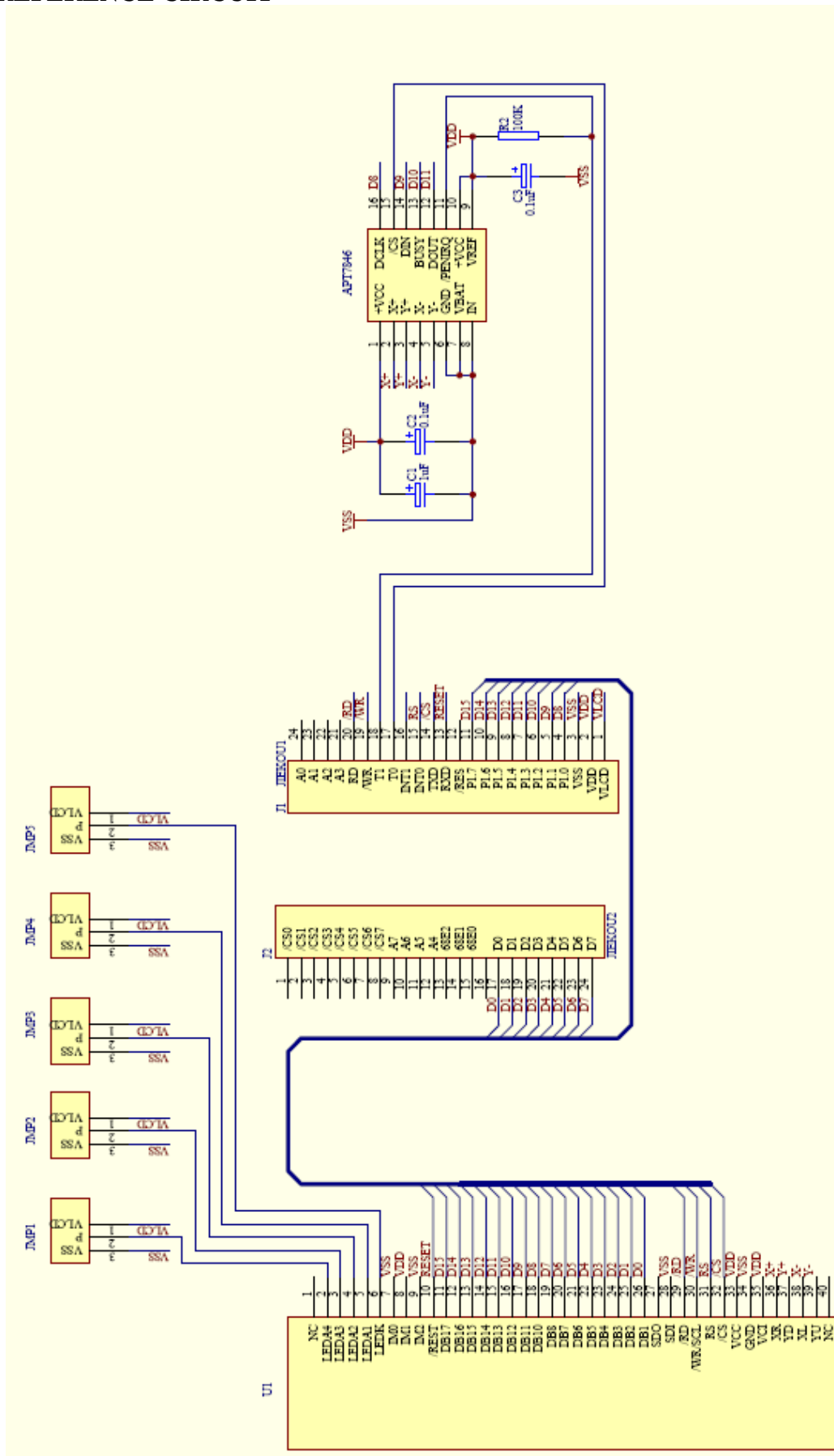
11.6 Storage

When long term storage is required, following precautions are necessary:

- 1) Storage them in a sealed polyethylene bag (antistatic), seal the opening, and store it where it is not subjected to direct sunshine, or to the light of fluorescent lamp. If properly sealed, there is no need for desiccant.
- 2) Store them in the temperature range of $-30^{\circ}\text{C}\sim 80^{\circ}\text{C}$ and at low humidity is recommended.

12. APPLICATION

12.1 REFERENCE CIRCUIT



12.2 APPENDIX

INITIALIZATION FOR REFERENCE (MPU: AT89C512):

```
void LCD_Init()
{
LCD_CtrlWrite(0x00);LCD_DataWrite(0x0000);
LCD_CtrlWrite(0x00);LCD_DataWrite(0x0000);
delay(100);
LCD_CtrlWrite(0x00);LCD_DataWrite(0x0000);
LCD_CtrlWrite(0x00);LCD_DataWrite(0x0000);
LCD_CtrlWrite(0x00);LCD_DataWrite(0x0000);
LCD_CtrlWrite(0x00);LCD_DataWrite(0x0000);
LCD_CtrlWrite(0xA4);LCD_DataWrite(0x0001);
delay(100);
LCD_CtrlWrite(0x60);LCD_DataWrite(0xA700);
LCD_CtrlWrite(0x08);LCD_DataWrite(0x0808);
/*****/
//Gamma Setting:
LCD_CtrlWrite(0x30);LCD_DataWrite(0x0203);
LCD_CtrlWrite(0x31);LCD_DataWrite(0x080F);
LCD_CtrlWrite(0x32);LCD_DataWrite(0x0401);
LCD_CtrlWrite(0x33);LCD_DataWrite(0x050B);
LCD_CtrlWrite(0x34);LCD_DataWrite(0x3330);
LCD_CtrlWrite(0x35);LCD_DataWrite(0x0B05);
LCD_CtrlWrite(0x36);LCD_DataWrite(0x0005);
LCD_CtrlWrite(0x37);LCD_DataWrite(0x0F08);
LCD_CtrlWrite(0x38);LCD_DataWrite(0x0302);
LCD_CtrlWrite(0x39);LCD_DataWrite(0x3033);
/*****/
//Power Setting:
LCD_CtrlWrite(0x90);LCD_DataWrite(0x0018);//80Hz
LCD_CtrlWrite(0x10);LCD_DataWrite(0x0530);//BT,AP
LCD_CtrlWrite(0x11);LCD_DataWrite(0x0237);//DC1,DC0,VC
LCD_CtrlWrite(0x12);LCD_DataWrite(0x01BF);
LCD_CtrlWrite(0x13);LCD_DataWrite(0x1000);//VCOM
delay(200);
/*****/
LCD_CtrlWrite(0x01);LCD_DataWrite(0x0100);
LCD_CtrlWrite(0x02);LCD_DataWrite(0x0200);
LCD_CtrlWrite(0x03);LCD_DataWrite(0x1030);
LCD_CtrlWrite(0x09);LCD_DataWrite(0x0001);
LCD_CtrlWrite(0x0A);LCD_DataWrite(0x0008);
LCD_CtrlWrite(0x0C);LCD_DataWrite(0x0000);
LCD_CtrlWrite(0x0D);LCD_DataWrite(0xD000);
```

```
LCD_CtrlWrite(0x0E);LCD_DataWrite(0x0030);
LCD_CtrlWrite(0x0F);LCD_DataWrite(0x0000);
LCD_CtrlWrite(0x20);LCD_DataWrite(0x0000);//H Start
LCD_CtrlWrite(0x21);LCD_DataWrite(0x0000);//V Start
LCD_CtrlWrite(0x29);LCD_DataWrite(0x002E);
LCD_CtrlWrite(0x50);LCD_DataWrite(0x0000);
LCD_CtrlWrite(0x51);LCD_DataWrite(0x00EF);
LCD_CtrlWrite(0x52);LCD_DataWrite(0x0000);
LCD_CtrlWrite(0x53);LCD_DataWrite(0x013F);
LCD_CtrlWrite(0x61);LCD_DataWrite(0x0001);
LCD_CtrlWrite(0x6A);LCD_DataWrite(0x0000);
LCD_CtrlWrite(0x80);LCD_DataWrite(0x0000);
LCD_CtrlWrite(0x81);LCD_DataWrite(0x0000);
LCD_CtrlWrite(0x82);LCD_DataWrite(0x005F);
LCD_CtrlWrite(0x93);LCD_DataWrite(0x0701);
/*****/
LCD_CtrlWrite(0x07);LCD_DataWrite(0x0100);
delay(100);
}
```